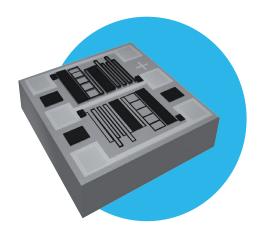
### Resistors

# Wire Bondable **Chip Resistors**

#### **WBC Series**

- Discrete or tapped schematics
- MIL inspection available
- High resistor density







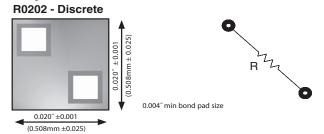
All parts are Pb-free and comply with EU Directive 2011/65/EU (RoHS2)

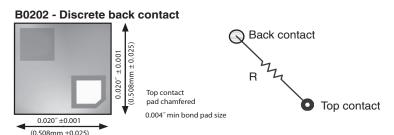
IRC's WBC series wire bondable chip resistors are ideally suited for the most demanding hybrid application. The WBC combines IRC's

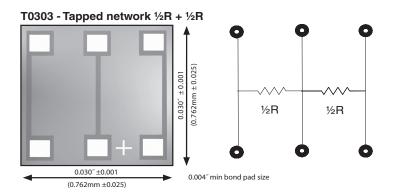
TaNSil® tantalum nitride thin film technology with silicon substrate processing to produce an extremely small footprint device with the proven stability, reliability and moisture performance of IRC's TaNSil® resistor film.

Available in a wide range of tolerances and temperature coefficients to fit a variety of hybrid circuit applications. Custom resistance values, sizes and schematics are available on request from the factory.

### Physical Data







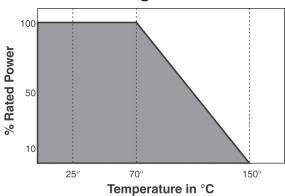
#### **Electrical Data**

Absolute Tolerance		to ±0.1%	
Absolute TCR		to ±25ppm/°C	
Package Power Rating (@ 70°C)		250mW	
Rated Operating Voltage (not to exceed $\sqrt{P \times R}$ )		100V	
Operating Temperature		-55°C to +150°C	
Noise		<-30dB	
Substrate Material		Oxidized Silicon (10KÅ SiO <sub>2</sub> min)	
Substrate Thickness		0.010" ±0.001 (0.254mm ±0.025)	
Bond Pad Metallization	Aluminum	10KÅ minimum	
	Gold	15KÅ minimum	
Backside	R0202 and T0303	Silicon (Al / Au optional)	
	B0202	3KÅ Au minimum 10KÅ Al minimum	
Passivation		Silicon Dioxide or Silicon Nitride	

**WBC Series** 



### **Power Derating Data**



## TCR/Inspection Code Table

Absolute TCR	Commercial Code	MIL Inspection Code*	
±300ppm/°C	00	04	
±100ppm/°C	01	05	
±50ppm/°C	02	06	
±25ppm/°C	03	07	

\*Notes: Product supplied to Class H of MIL-PRF 38534 includes 100% visual inspection

## Manufacturing Capabilities Data

Resistance Range	Package	Available Abs Tolerances	Available Ratio Tol (T0303 only)	Best Absolute TCR	Tracking TCR (T0303 only)
10Ω - 20Ω	0202 only	GlK	N/A	+-100ppm/C	N/A
21Ω - 50Ω	0202 and 0303	FGJK	FGJ	+-100ppm/C	+-50ppm/C
51Ω - 100Ω	0202 and 0303	CDFGJK	CDFGJ	+-100ppm/C	+-25ppm/C
101Ω - 200Ω	0202 and 0303	CDFGJK	CDFGJ	+-50ppm/C	+-10ppm/C
201Ω - 500Ω	0202 and 0303	BCDFGJK	BCDFGJ	+-50ppm/C	+-5ppm/C
501Ω - 999Ω	0202 and 0303	BCDFGJK	BCDFGJ	+-25ppm/C	+-2ppm/C
1.0ΚΩ - 400ΚΩ	0202 and 0303	BCDFGJK	ABCDFGJ	+-25ppm/C	+-2ppm/C
401ΚΩ - 800ΚΩ	0303 only	BCDFGJK	ABCDFGJ	+-25ppm/C	+-2ppm/C

www.ttelectronicsresistors.com

### Wire Bondable **Chip Resistors**

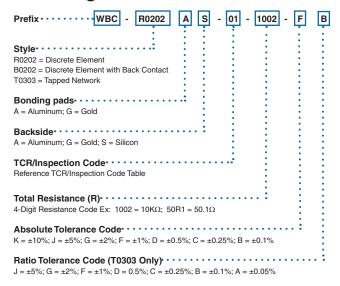




### **Environmental Data**

Test	Method	Max ∆R	Typical ∆R
Thermal Shock	MIL-STD-202 Method 107 Test condition F	±0.1%	±0.02%
High Temperature Exposure	MIL-STD-883 Method 1008 150°C, 1000 hours	±0.1%	±0.05%
Low Temperature Storage	-55°C, 1000 hours	±0.03%	±0.01%
Life	MIL-STD-202 Method 108 70°C, 1000 hours	±0.5%	±0.01%
Life at Elevated Temperature	MIL-STD-202 Method 108 125°C, 1000 hours	±0.5%	±0.05%

### **Ordering Data**



**Packaging**Standard packaging is 2" x 2" chip tray. For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.